

IN THE CLAIMS

1. - 11. (Cancelled)

12. (Previously Presented) A method of manufacturing an image forming apparatus comprising the steps of:

- arranging on a support member a substrate having a conductor and a wiring line connected to the conductor;
- covering the conductor on the substrate with a vessel except for part of the wiring line;
- setting a desired atmosphere in the vessel;
- applying a voltage to the conductor via the part of the wiring line;
- removing the vessel from the substrate; and
- combining a face plate having image forming substances and the substrate from which the vessel has been removed.

13. (Previously Presented) The method according to claim 12, wherein the step of setting the desired atmosphere in the vessel comprises the step of evacuating an interior of the vessel.

14. (Previously Presented) The method according to claim 12, wherein the step of setting the desired atmosphere in the vessel comprises the step of introducing gas into the vessel.

15. (Previously Presented) The method according to claim 12, further comprising the step of fixing the substrate to the support member.

16. (Previously Presented) The method according to claim 15, wherein the step of fixing the substrate to the support member comprises the step of vacuum-chucking the substrate and the support member.

17. (Previously Presented) The method according to claim 15, wherein the step of fixing the substrate to the support member comprises the step of electrostatically chucking the substrate and the support member.

18. (Previously Presented) The method according to claim 12, wherein the step of arranging the substrate on the support member comprises arranging a heat conduction member between the substrate and the support member.

19. (Previously Presented) The method according to claim 12, wherein the step of applying the voltage to the conductor comprises the step of controlling a temperature of the substrate.

20. (Previously Presented) The method according to claim 12, wherein the step of applying the voltage to the conductor comprises the step of heating the substrate.

21. (Previously Presented) The method according to claim 12, wherein the step of applying the voltage to the conductor comprises the step of cooling the substrate.

22. (Previously Presented) A method of manufacturing an image forming apparatus comprising the steps of:

arranging on a support member a substrate on which a plurality of devices, each having a pair of electrodes and a conductive film arranged between the pair of electrodes, and wiring lines which connect the plurality of devices are formed;

covering the plurality of devices on the substrate with a vessel except for part of the wiring lines;

setting a desired atmosphere in the vessel;

applying a voltage to the plurality of devices via the part of the wiring lines;

removing the vessel from the substrate; and

combining a face plate having image forming substances and the substrate from which the vessel has been removed.

23. (Previously Presented) A method of manufacturing an image forming apparatus comprising the steps of:

arranging on a support member a substrate on which a plurality of devices, each having a pair of electrodes and a conductive film arranged between the pair of electrodes, and a plurality of X-direction wiring lines and a plurality of Y-direction wiring lines which connect the plurality of devices in a matrix are formed;

covering the plurality of devices on the substrate with a vessel except for part of the plurality of X-direction wiring lines and the plurality of Y-direction wiring lines;

setting a desired atmosphere in the vessel;

applying a voltage to the plurality of devices via the part of the plurality of X-direction wiring lines and the plurality of Y-direction wiring lines;

removing the vessel from the substrate; and

combining a face plate having image forming substances and the substrate from which the vessel has been removed.

24. (Previously Presented) The method according to claim 22, wherein the step of setting the desired atmosphere in the vessel comprises the step of evacuating an interior of the vessel.

25. (Previously Presented) The method according to claim 22, wherein the step of setting the desired atmosphere in the vessel comprises the step of introducing gas into the vessel.

26. (Previously Presented) The method according to claim 22, further comprising the step of fixing the substrate to the support member.

27. (Previously Presented) The method according to claim 26, wherein the step of fixing the substrate to the support member comprises the step of vacuum-chucking the substrate and the support member.

28. (Previously Presented) The method according to claim 26, wherein the step of fixing the substrate to the support member comprises the step of electrostatically chucking the substrate and the support member.

29. (Previously Presented) The method according to claim 22, wherein the step of arranging the substrate on the support member comprises arranging a heat conduction member between the substrate and the support member.

30. (Previously Presented) The method according to claim 22, wherein the step of applying the voltage to the devices comprises the step of controlling a temperature of the substrate.

31. (Previously Presented) The method according to claim 22, wherein the step of applying the voltage to the devices comprises the step of heating the substrate.

32. (Previously Presented) The method according to claim 22, wherein the step of applying the voltage to the devices comprises the step of cooling the substrate.

33. (Previously Presented) A method of manufacturing an image forming apparatus, comprising the steps of:

arranging on a support member a substrate on which a plurality of devices, each having a pair of electrodes and a conductive film arranged between the pair of electrodes, and wiring lines which connect the plurality of devices are formed;

covering the plurality of devices on the substrate with a vessel except for part of the wiring lines;

setting a first atmosphere in the vessel;
applying a voltage to the plurality of devices via the part of the wiring lines in the first atmosphere;
setting a second atmosphere in the vessel;
applying a voltage to the plurality of devices via the part of the wiring lines in the second atmosphere;
removing the vessel from the substrate; and
combining a face plate having image forming substances and the substrate from which the vessel has been removed.

34. (Previously Presented) A method of manufacturing an image forming apparatus comprising the steps of:
arranging on a support member a substrate on which a plurality of devices, each having a pair of electrodes and a conductive film arranged between the pair of electrodes, and a plurality of X-direction wiring lines and a plurality of Y-direction wiring lines which connect the plurality of devices in a matrix are formed;
covering the plurality of devices on the substrate with a vessel except for part of the plurality of X-direction wiring lines and the plurality of Y-direction wiring lines;
setting a first atmosphere in the vessel;

applying a voltage to the plurality of devices via the part of the plurality of X-direction wiring lines and the plurality of Y-direction wiring lines in the first atmosphere;

setting a second atmosphere in the vessel;

applying a voltage to the plurality of devices via the part of the plurality of X-direction wiring lines and the plurality of Y-direction wiring lines in the second atmosphere;

removing the vessel from the substrate; and

combining a face plate having image forming substances and the substrate from which the vessel has been removed.

35. (Previously Presented) The method according to claim 33, wherein the step of setting the first atmosphere in the vessel comprises the step of evacuating an interior of the vessel.

36. (Previously Presented) The method according to claim 33, wherein the step of setting the second atmosphere in the vessel comprises the step of introducing gas containing a carbon compound into the vessel.

37. (Previously Presented) The method according to claim 33, further comprising the step of fixing the substrate to the support member.

38. (Previously Presented) The method according to claim 37, wherein the step of fixing the substrate to the support member comprises the step of vacuum-chucking the substrate and the support member.

39. (Previously Presented) The method according to claim 37, wherein the step of fixing the substrate to the support member comprises the step of electrostatically chucking the substrate and the support member.

40. (Previously Presented) The method according to claim 33, wherein the step of arranging the substrate on the support member comprises arranging a heat conduction member between the substrate and the support member.

41. (Currently Amended) The method according to claim 33, wherein the steps of applying the voltage to the devices in the first ~~atmosphere and/or~~ and the second atmosphere comprise[[s]] the step of controlling a temperature of the substrate.

42. (Currently Amended) The method according to claim 33, wherein the steps of applying the voltage to the devices in the first ~~atmosphere and/or~~ and the second atmosphere comprise[[s]] the step of heating the substrate.

43. (Currently Amended) The method according to claim 33, wherein the steps of applying the voltage to the devices in the first ~~atmosphere and/or~~ and the second atmosphere comprise[[s]] the step of cooling the substrate.